



TECHNICAL DATA SHEET

00388: FLEXcure B-Stage High Performance Thermosetting Adhesive

Arlon Innovations' Phenolic based adhesive system is ideally applied to many substrates including Aramid paper, Polyimide film, PET film, Aluminum foil, Copper foil, and stainless steel. The adhesive is applied to the substrate in b-stage form. Once b-staged, the adhesive and substrate can be heated and pressed for full cure bonding.

PRODUCT ATTRIBUTES

- Superior thermal stability, electrical properties, and chemical resistance
- Extremely High continuous temperature resistance
- Very low outgassing
- Tack free at room temperature – no release liner is needed
- RoHS and REACH compliant

REPRESENTATIVE PHYSICAL PROPERTIES		
PROPERTY	VALUE	TEST METHOD
VISCOSITY (cP)	600 - 900	RH spindle #2, 20 rpm
PERCENT SOLIDS	24% - 28%	ALT 081
180° PEEL ADHESION (stainless steel) 7 mil AL foil	> 30 lb/in	ASTM D3330
RECOMMENDED B-STAGE TEMP (°F)	210 - 260	
RECOMMENDED CURING PARAMETERS Temp, °F Time, min Pressure, psi	310 – 350 30 25 - 75	
CONTINUOUS USE TEMP (°F)	800	

Curing parameters are application specific. It is highly recommended that optimal temperature, time and pressure be determined for each specific application.

This product complies with RoHS (Restriction of Hazardous Substances) Directive, citation 2002/95/EC. Arlon Innovations does not manufacture this material using any of the banned substances listed in the directive guidelines as of July 1, 2008.

STORAGE

- Shelf life: one (1) year from the date of shipment.
- Store in a clean area free from exposure to excessive heat, moisture, or direct sunlight (50°F to 80°F).

Product performance will vary in each application and is dependent upon composite construction. Arlon Innovations does not guarantee the replication of this data by third parties. None of the data or statements contained herein is intended to warrant the performance of this product. Data is representative and not intended as a manufacturing specification.